3D Packaging and Integration Japan TC Chapter

Japan Standards Winter Meetings 2025

Monday, February 3, 2025

Room 1, SEMI Japan, Tokyo, Japan/ Official Virtual TC Chapter Meeting (Hybrid)

2:00 PM – 5:00 PM JST

AGENDA

1 Welcome/Call to Order

1.1 Introductions

1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)

1.3 Agenda Review

2 Review of Previous Meeting Minutes

3 Liaison Report

3.1 JRSC Report

3.2 GCS Report

3.3 North America TC Chapter

3.4 Taiwan TC Chapter

4 Staff Report

5 Ballot Review

5.1 Doc.#7300, Line Item Revision to SEMI G96-1014 (Reapproved 1019), Test Method for Measurement of Chip (Die) Strength by mean of Cantilever Bending

6 Subcommittee & Task Force Reports

6.1 3DS IC Bonded Layer Inspection Metrology Task Force

6.2 Wafer Bond Strength Measurement by Double-cantilever Beam Task Force

6.3 3D Packaging & Integration 5-Year Review Task Force

6.4 3D Packaging & Integration Steering Group

7 Old Business

7.1 Project Period Review

7.2 5-Year Review

8 New Business

9 Action Item Review

9.1 Open Action Items

Item #	*Assigned to*	*Details*
3DP&I_20241028-01	SEMI Staff	To forward the result of ballot review for Doc.#7252 to the ISC A&R SC for procedural review.
3DP&I_20241028-02	5 year review TF	To submit G98 Line Item Revision ballot for Cycle 9.

9.2 New Action Items

Item #	*Assigned to*	*Details*

10 Next Meeting and Adjournment